1	L Number	Hits	Search Text	DB I	Time stamp
"Al") with (pad or electrode) and barrier with "Ni" or nickel) and (copper or "Cu") near (layers or films) and solder with electrode and barrier with (pad or electrode) and barrier and solder with electrode and barrier with "Ni" or nickel) and (copper or "Cu") and solder with electrode and barrier with "Ni" or nickel) with (copper or "Cu") and solder with electrode and barrier electrode and solder with electrode and barrier with "Ni" or nickel) with (copper or "Cu") and solder with electrode and barrier electrode and copper or "Cu") and solder with electrode and copper or "Cu" and solder with electrode and charrier or UBH) with (pad or electrode) and (barrier or IBM) with "Ni" or nickel) and (copper or "Cu") and solder with electrode) and charrier or IBM with "Ni" or nickel) and (looper or "Cu") and solder with electrode) and charrier or IBM) with "Ni" or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") and solder with electrode) and charrier or IBM) with "Ni" or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") and solder with under-bump near metallurgy or UBM) with (copper or "Cu") and solder with US-PGPUB; EPG, JPO; DERWENT; IBM TOB US-PGPUB; EPG, JPO; DERWENT; IBM					
with ("Ni" or nickel) and (copper or "Cu")   near (layers or films) and solder with outcottic   1257/737 or 257/786) and (aluminum or "Al") with (pad or electrode) and barrier with ("Ni" or nickel) and (copper or "Cu")   1587   158	- /	, i			
16   16   17/37   17   17/38   18   16   18   18   18   18   18   1				]	
16   (257/737 or 257/786) and (aluminum or "Al") with (pad or electrode) and barrier with ("Ni" or nickel) and (copper or "Cu") and solder with eutectic with ("Ni" or nickel) and (copper or "Cu") and solder with ("Ni" or nickel) and (copper or "Cu") and solder with ("Ni" or nickel) with (copper or "Cu") and solder with ("Ni" or nickel) with (copper or "Cu") and solder with eutectic or TBM) with ("Ni" or nickel) and (upper near harrier or UBM) with ("Ni" or nickel) and (upper near near harrier or UBM) with ("Ni" or nickel) and (upper near nickel) and (upper nickel) and (upper near nickel) and (upper			near (layers or films) and solder with	ļ	
"Al"   with (pad or electrode) and barrier with ("Ni" or nickel) and (copper or "Cu") and solder with eutectic   USPAT   2004/05/26 19:18					
### With ("Ni" or nickel) and (copper or "Cu") and solder with eutectic (257/737 or 257/786) and (aluminum or "Al") with (pad or electrode) and barrier with ("Ni" or nickel) with (copper or "Cu") and solder with eutectic (257/737 or 257/786) and (aluminum or "Al") with (pad or electrode) and (barrier or 18M) with ("Ni" or nickel) and (luprier or nickel) and (copper or "Cu") with (pad or electrode) and (barrier or 18M) with ("Ni" or nickel) and (lupper near barrier or UBM) with (copper or "Cu") with (pad or electrode) and (barrier or 18M) with ("Ni" or nickel) and (under-bump near metal or cirsuit) and (copper or "Cu") with (pad or electrode) and (lunder-bump near metal lury or UBM) with (copper or "Cu") with (pad or electrode) and (lunder-bump near metal lury or UBM) with (copper or "Cu") and solder with eutectic  53 3153  3153  3153  3257/737 and barrier with pad  USPAT  USPAT  USPAT  USPAT  USPAT  USPAT  2004/05/26 19:23  USPAT  2004/05/26 19:23  USPAT  USPAT  USPAT  2004/05/26 19:23  2004/05/26 19:23  2004/05/26 20:53  USPAT: US	48	16		USPAT	2004/05/26 19:17
### and solder with entectic					
### 19  ### 19		İ			
"Al") with (pad or electrode) and barrier with ("Ni" or nickel) with (copper or "Cu") and solder with eutectic or IBM) with ("Ni" or nickel) and (lauminum or "Al") with (pad or electrode) and (barrier or IBM) with (wish eutectic (aluminum or "Al") with (moper or "Cu") and solder with eutectic (aluminum or "Al") with (moper or "Cu") and solder with eutectic (aluminum or "Al") with (wir30 or metal or cirsuit) and (copper or "Cu") with (pad or electrode) and (barrier or IBM) with ("Ni" or nickel) and (upper near barrier or UBM) with ("Su" or nickel) and (partier or IBM) with ("Ni" or nickel) and (partier or IBM) with ("Ni" or nickel) and (barrier or IBM) with ("Ni" or nickel) and (lauder-bump near metallurgy or UBM) with (copper or "Cu") and solder with eutectic (USPAT) (U	49	g		IISPAT	2004/05/26 19:18
with ("Ni" or nickel) with (copper or "Cu") and solder with eutectic or 1RM) with (gad or electrode) and (barrier or IRM) with ("Ni" or nickel) and (upper near barrier or UBM) with (copper or "Cu") and solder with eutectic or electrode) and down with ("Ni" or nickel) and (upper near barrier or UBM) with (wis" or nickel) and (copper or "Cu") with (pad or electrode) and (barrier or IBM) with ("Ni" or nickel) and (upper near barrier or UBM) with (copper or "Cu") with (pad or electrode) and (barrier or IBM) with ("Ni" or nickel) and (upper near barrier or UBM) with (copper or "Cu") with (pad or electrode) and (barrier or LBM) with ("Ni" or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") with (pad or electrode) and (barrier or LBM) with ("Ni" or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") and solder with electrode) and (barrier or LBM) with ("Ni" or nickel) and (under-bump near metallurgy or UBM) with copper or "Cu") with (pad or electrode) and (barrier or LBM) with ("Ni" or nickel) and ("SPAT" or JPO"	30	ĭ			2001,00,20 23,20
"Cu"   and solder with eutectic   3   3   257/737   and solder with (eluminum or "Al") with (pad or electrode) and (barrier or IBM) with ("Ni" or nickel) and (upper near barrier or UBM) with (copper or "Cu") and solder with eutectic   (aluminum or "Al") with (wir\$3 or metal or cirsuit) and (copper or "Cu") with (pad or electrode) and (barrier or IBM) with ("Ni" or nickel) and (upper near barrier or UBM) with ("Ni" or nickel) and (upper near barrier or UBM) with ("Su" or nickel) and (upper near barrier or UBM) with ("Su" or nickel) and (copper or "Cu") with (pad or cirsuit) and (copper or "Cu") with (pad or cirsuit) and (copper or "Cu") with (pad or cirsuit) and (copper or "Cu") and solder with eutectic   USPAT   US-ECPUB; EFO; JPO; DERMENT; IBM TOB   USPAT; US-ECPUB; EFO; JPO; DERMENT; IBM T					
"Al", with (pad or electrode) and (barrier or LBM) with ("Ni" or nickel) and (upper near barrier or UBM) with (copper or "Cu") with (pad or electrode) and solder with eutectic (aluminum or "Al") with (wirs3 or metal or circuit) and (copper or "Cu") with (pad or electrode) and (barrier or IBM) with ("Ni" or nickel) and (copper or "Cu") with (pad or electrode) and (barrier or IBM) with ("Ni" or nickel) and (copper or "Cu") with (pad or electrode) and (barrier or LBM) with ("Ni" or nickel) and (copper or "Cu") with (pad or electrode) and (barrier or LBM) with ("Ni" or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") and solder with eutectic (aluminum or "Al") with ("Ni" or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") and solder with eutectic (aluminum or "Cu"					
or IBM) with ("Ni" or nickel) and (upper near barrier or UBM) with (copper or "Cu") and solder with eutectic (aluminum or "Al") with (wir\$3 or metal or cirsuit) and (copper or "Cu") with (page or nickel) and (upper near barrier or UBM) with (copper or "Cu") and solder with eutectic (aluminum or "Al") with (wir\$3 or metal or cirsuit) and (copper or "Cu") and solder with eutectic (aluminum or "Al") with (wir\$3 or metal or cirsuit) and (copper or "Cu") with (pad or electrode) and (barrier or LBM) with ("Ni" or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") and solder with eutectic (beautiful or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") and solder (beautiful or nickel) and barrier with pad (beautiful or nickel) (b	50	3		USPAT	2004/05/26 19:19
near barrier or UBM) with (copper or "Cu")   and solder with eutectic (aluminum or "Al") with (wirs3 or metal or cirsuit) and (copper or "Cu") with (pad or electrode) and (barrier or IBM) with ("Ni" or nickel) and (upper near barrier or UBM) with (copper or "Cu") with (pad or electrode) and (barrier or IBM) with (pad or electrode) and (barrier or IBM) with (pad or electrode) and (barrier or LBM) with (pad or electrode) and barrier with pad USPAT; US-PGPUB; EPO; JPO; DERMENT; LBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; LBM					
2004/05/26 19:23   2004/05/26 20:33   2004/05/26					
1					
Cirsuit) and (copper or "Cu") with (pad or electrode) and (barrier or IBM) with ("Nu" or nickel) and (upper near barrier or UBM) with (copper or "Cu") and solder with eutectic (aluminum or "Al") with (wiss or metal or cirsuit) and (copper or "Cu") with (pad or electrode) and (barrier or LBM) with ("Nu" or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") and solder with eutectic USPAT; US-FGFUB; EPG; JPG; DERWENT; IBM TDB USPAT; US-FGFUB; EPG; JPG; DERWENT; US-FGFUB; EPG; JPG; DE	51	7		USPAT	2004/05/26 19:23
electrode   and (barrier or IBM) with ("Ni" or nickel) and (upper near barrier or UBM) with (copper or "Cu") and solder with electrode   electrode   and (copper or "Cu") with (pad or clesurial) with (copper or "Cu") with (pad or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") and solder with electrode   257/737   USPAT; USPAC; USPAT; USPAC; USPAT; U		<i>'</i>			
### (copper or "Cu") and solder with eletectic (aluminum or "Al") with (wirs3 or metal or cirsuit) and (copper or "Cu") with (pad or electrode) and (barrier or LBM) with ("Ni" or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") and solder with electic 257/737    3153   3153   257/737   USPAT; USP-GPUB; EPO, JPO, DERWENT; IBM TDB USPAT; USP-GPUB; EPO, JPO, DERWENT; USP-GPUB; E					
Second Composition   Second			or nickel) and (upper near barrier or UBM)		
Section   Sect					
cirsuit) and (copper or "Cu") with (pad or electrode) and (barrier or LBM) with ("Ni" or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") and solder with eutectic 257/737  3153  3153  3153  327737  32004/05/26 20:53  327737  32004/05/26 20:53  3257/737  32004/05/26 20:53  3257/737  32004/05/26 19:46  3257/737 and barrier with pad  3257/737 and pad  3257/737 and pad and wir\$3  32004/05/26 19:46  3257/737 and pad and wir\$3  32004/05/26 20:38  3257/738  32004/05/26 20:39  3257/738  32004/05/26 20:39  3257/738  32004/05/26 20:39  3257/738  32004/05/26 20:39  3257/738  32004/05/26 20:39  3257/738  32004/05/26 20:39  3257/738  32004/05/26 20:39  3257/738				110271	2004/05/20 10 22
electrode   and (barrier or LBM) with ("Ni" or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") and solder with eutectic   257/737   USPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; USPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPA	52	8	(aluminum or "Al") with (wir\$3 or metal or	USPAT	2004/05/26 19:23
or nickel) and (under-bump near metallurgy or UBM) with (copper or "Cu") and solder with eutectic 257/737 US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPAT; US-PGPUB; EPG; JPG; DERWENT; US-PGP					
Sample   S					
SPAT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB   SPAT; US-PGPUB; EPG					
Second   S					
Second   S	53	3153	257/737		2004/05/26 20:53
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPAD; USPAT; U		İ		1	
Second   S					
54				1	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB	54	226	257/737 and barrier with pad		2004/05/26 19:46
DERWENT;   IBM_TDB   USPĀT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPĀT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPĀT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPĀT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPĀT;	0.				
Second   S				EPO; JPO;	
55					
US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EFO; JPO; DERWENT; US-PGPUB; EFO; JPO; DERWE		0.440	057/707		2004/05/26 10-46
EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT); IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT); IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	55	2440	25///3/ and pad		2004/05/26 19:46
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;					
56 1898 257/737 and pad and wir\$3 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; E					
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;				IBM_TDB	
57 0 (257/737 and pad and wir\$3) not (257/737 US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO;	56	1898	257/737 and pad and wir\$3	1	2004/05/26 20:38
57 0 (257/737 and pad and wir\$3) not (257/737					
57 0 (257/737 and pad and wir\$3) not (257/737 US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; EPO;					
57 0 (257/737 and pad and wir\$3) not (257/737 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; D					
and pad)  and pad)  58  542 (257/737 and pad) not (257/737 and pad and wir\$3)  59  1255 257/737 not (257/737 and pad and wir\$3)  60  2623 257/738  US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGPUB; EPO; JPO; DERWENT;	57		(257/737 and pad and wir\$3) not (257/737		2004/05/26 20:38
58 542 (257/737 and pad) not (257/737 and pad usr\$3)  59 1255 257/737 not (257/737 and pad and wir\$3)  60 2623 257/738  EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	~ /			I	
58 542 (257/737 and pad) not (257/737 and pad USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;			•	1	
58 542 (257/737 and pad) not (257/737 and pad USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;				1	
and wir\$3)  and wir\$3)  1255 257/737 not (257/737 and pad and wir\$3)  257/738 US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;				_	0004/05/05 00 00
EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;	58	542			2004/05/26 20:39
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;			and wir\$3)		
59 1255 257/737 not (257/737 and pad and wir\$3) IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;				1	
59 1255 257/737 not (257/737 and pad and wir\$3) USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;				•	
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	59	1255	257/737 not (257/737 and pad and wir\$3)	_	2004/05/26 20:39
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;				i	
60 2623 257/738 IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;					
60 2623 257/738 USPĀT; US-PGPUB; EPO; JPO; DERWENT;				-	
US-PGPUB; EPO; JPO; DERWENT;	60	2622	257/738	_	2004/05/26 21.14
EPO; JPO; DERWENT;	00	2023	231/130		2007/03/20 21.14
DERWENT;					
IBM TDB				DERWENT;	
		<u> </u>		IBM TDB	

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61	2150	257/738 and pad	USPAT;	2004/05/26 21:05
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
62	1234	257/738 and pad with wir\$3	USPĀT;	2004/05/26 20:56
•			US-PGPUB;	
ļ			EPO; JPO;	
			DERWENT; IBM TDB	
63	14	5705428.pn. or	USPAT;	2004/05/26 21:01
		5937320.pn. or	US-PGPUB;	
		6127731.pn. or	EPO; JPO;	
		6140703.pn. or	DERWENT;	
		6293457.pn. or 6306751.pn. or	IBM_TDB	
		6373137.pn.		
64	7	5705428.pn. or 5937320.pn. or	USPAT	2004/05/26 21:01
		6127731.pn. or		
		6140703.pn. or		
		6293457.pn. or		
		6306751.pn. or		
65	916	6373137.pn. (257/738 and pad) not (257/738 and pad	USPAT;	2004/05/26 21:05
""		with wir\$3)	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
	001	057/720	IBM TDB	2004/05/26 22:15
66	281	257/739	USPAT; US-PGPUB;	2004/05/26 22:15
			EPO; JPO;	
	i		DERWENT;	
		,	IBM_TDB	
67	2501	257/786	USPAT;	2004/05/26 21:17
			US-PGPUB; EPO; JPO;	
		·	DERWENT;	·
	•		IBM_TDB	
68	2000	257/786 and pad	USPAT;	2004/05/26 22:06
1			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
69	501	257/786 not (257/786 and pad)	USPAT;	2004/05/26 22:09
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
70	17	(semiconductor or die or chip or IC) with	USPAT;	2004/05/26 22:14
	]	(trench or recess or groove) with top near	US-PGPUB;	
		surface and (pad or electrode or contact)	EPO; JPO;	
		with slits	DERWENT; IBM TDB	
71	196	(semiconductor or die or chip or IC) and	USPAT;	2004/05/26 22:20
' -	196	(trench or recess or groove) with upper	US-PGPUB;	
		near surface and (pad or electrode or	EPO; JPO;	
		contact) with slits	DERWENT;	
7.0	1010	257/750	IBM_TDB USPAT;	2004/05/26 22:39
72	1919	257/750	US-PGPUB;	2004/03/20 22:39
	]		EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/05/05 55 55
73	231		USPAT;	2004/05/26 22:31
		(trench or recess or groove) with align\$4 and (pad or electrode or contact) with	US-PGPUB; EPO; JPO;	
		slits	DERWENT;	
		_	IBM_TDB	
80	1645		USPAT	2004/05/26 22:33
		(trench or recess or groove) with align\$4		
		and (pad or electrode or contact) with (channels)		j
		(Citalilie13)	L	

Ctrench or recess or groove) with align\$4 and (pad or contact) with (channels)   USPAT; US-PCPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; US-PCPUB; EPC; JPC; DERWENT; US-PCPUB; EPC;	81	1103	(semiconductor or die or chip or IC) and	USPAT	2004/05/26 22:34
82 2445 257/751 and (pad or contact) with (channels) 257/751 Septimental 257/751 Septi					
82					
83 393 257/751 and pad and barrier USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB;	82	2445		USPAT;	2004/05/26 22:39
BERMENT;   IBM_TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERWENT;   US-PGPUB;   EPO; JPO;   DERWENT;   US-PGPUB;   EPO; JPO;   DERWENT;   EPO; JPO;				US-PGPUB;	
Same				EPO; JPO;	
83 393 257/751 and pad and barrier USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB USPĀT; US-PGPUB; EPG; JPG; DERWENT; EPG; DERWENT;				DERWENT;	
S-PGPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; US-PGPUB; EPC; JPC; DERWENT;				IBM TDB	
84 51 257/751 and pad and metallurgy	83	393	257/751 and pad and barrier	USPAT;	2004/05/26 22:40
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT; EPO; JPO; DERWENT; EPO; JPO; DERWENT;			-	US-PGPUB;	
84 51 257/751 and pad and metallurgy				EPO; JPO;	1
84 51 257/751 and pad and metallurgy USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EFO; JPO; DERWENT;				DERWENT;	
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT;					
### BPO; JPO; DERWENT;  ### DB	84	51	257/751 and pad and metallurgy		2004/05/26 22:41
85					.
124   (257/762 or 257/763 or 257/766) and pad   IBM_TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERWENT;   USPAT;					
85		ŀ		1	
and metallurgy    S-PGPUB; EPO; JPO; DERWENT; IBM_TDB   US-PGPUB; EPO; JPO; DERWENT; and metallurgy   US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT;					
EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; and metallurgy US-PTHB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;	85	124		,	2004/05/26 22:44
B6 212 (257/772 or 257/773 or 257/779) and pad and metallurgy (257/784 or 257/780 or 257/781) and pad and metallurgy (257/786 or 228/254) and pad and (257/786 or 228/254) and pad and (257/786 or 228/254) and pad and (257/786 or 228/254) and pad and (257/786 or 228/254) and pad and (257/786 or 228/254) and pad and (257/786 or 228/254) and pad and (257/786 or 228/254) and pad and (257/786 or 228/254) and pad and (257/786 or 228/254) and pad and (257/786 or 228/254) and pad and (257/786 or 228/254) and pad and (257/786 or 228/254) and pad and (257/786) (22:52 or 257/786) (257/			and metallurgy		
86 212 (257/772 or 257/773 or 257/779) and pad USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; and metallurgy US-784 or 257/780 or 257/781) and pad USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;					
86 212 (257/772 or 257/773 or 257/779) and pad uspAT; us-pGPUB; EPO; JPO; DERWENT; IBM TDB uspAT; and metallurgy us-pGPUB; EPO; JPO; DERWENT; and metallurgy us-pGPUB; EPO; JPO; DERWENT; IBM TDB uspAT; us-pGPUB; EPO; JPO; DERWENT; IBM TDB uspAT; us-pGPUB; EPO; JPO; DERWENT; us-pGPUB; EPO; JPO; DERWENT; us-pGPUB; EPO; JPO; DERWENT; us-pGPUB; EPO; JPO; DERWENT;			,		
and metallurgy  87  218 (257/784 or 257/780 or 257/781) and pad  and metallurgy  88  144 (257/786 or 228/254) and pad and  metallurgy  88  144 (257/786 or 228/254) and pad and  metallurgy  88  145 (257/786 or 228/254) and pad and  metallurgy  88  146 (257/786 or 228/254) and pad and  metallurgy  88  187  188 (257/786 or 228/254) and pad and  metallurgy  88  188 (257/786 or 228/254) and pad and  metallurgy  88  199 (257/786 or 228/254) and pad and  metallurgy  89  108-PGPUB;  EPO; JPO;  DERWENT;					
EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;	86	212	1 1		2004/05/26 22:49
87 218 (257/784 or 257/780 or 257/781) and pad USPAT; and metallurgy US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;			and metallurgy		
87 218 (257/784 or 257/780 or 257/781) and pad USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;					
87 218 (257/784 or 257/780 or 257/781) and pad USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; Metallurgy US-PGPUB; EPO; JPO; DERWENT;				I .	
and metallurgy  and metallurgy  US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; DERWENT;  WS-PGPUB; EPO; JPO; DERWENT;	0.7	212	/057/704 257/700 257/701\ 3	1	2004/05/26 22:52
EPO; JPO; DERWENT; IBM_TDB  144 (257/786 or 228/254) and pad and USPAT; US-PGPUB; EPO; JPO; DERWENT;    DERWENT;   DERWEN	0/	218		· ·	2004/03/26 22:52
DERWENT; IBM_TDB USPAT; Wetallurgy  DERWENT; US-PGPUB; EPO; JPO; DERWENT;			and mecaliurgy		
88 144 (257/786 or 228/254) and pad and USPAT; US-PGPUB; EPO; JPO; DERWENT;				1 ' '	
88 144 (257/786 or 228/254) and pad and USPAT; US-PGPUB; EPO; JPO; DERWENT; 2004/05/26 22:52				1	
metallurgy US-PGPUB; EPO; JPO; DERWENT;	99	144	(257/786 or 228/254) and mad and		2004/05/26 22:52
EPO; JPO; DERWENT;	00	144	1 · · · · · · · · · · · · · · · · · · ·		2004/05/20 22.52
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I IBM 'I'DB I				IBM TDB	